



揚博科技股份有限公司 Ampoc Far-East Co., Ltd

2023/09/27
Earnings call



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01

Ampoc Profile

Profile



Since
1976

Capital
11.4 Million

Turnover
34.48 Million

Employee
340 people

1980-1990

- Ampoc was founded with initial registered capital of NT\$1 million;
- TCM Japan established TTCM in CHUNG-LI industrial zone for PCB wet process equipment manufacture. Ampoc invested TTCM and obtained global exclusive distribution ship excluding Japan.

2001-2010

- Company name changed as “AMPOC FAR-EAST CO., LTD.,” capital increased to NT\$ 0.9 Billion.
- Ampoc (2493) was listed on the Taiwan Stock Exchange on 01/23/2002

2021- now

- ESG task force established.
- ECO Heat exchange System developed.

1976- Establishment

- Ampoc purchased the office in Taipei as headquarters.
- Ampoc was approved as IPO.
- AMPOC merged TTCM.

1991-2000

- “Ampoc Wing” was developed and shipped to customer for production usage.
- HK branch was approved by the board of directors.
- AMPOC Shanghai was invested by HK branch.

2011-2020

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Company Status



Company status

~AMPOC considers serving customers as its mission, and actively acts as a coordinator for information technology industry~



**MR. RONALD SU
(CEO & CHAIRMAN)**



- 2 divisions**
 - Manufacturing Management Division
 - Business Management Division



- 4 cores**
 - Advanced manufacture
 - Hi-tech R&D
 - Advanced semiconductor process
 - energy saving and carbon reduction



- 9 mindsets**
 - Quality first
 - innovation
 - profession
 - Process improvement
 - Engagement management
 - International marketing
 - Service first
 - Social responsibility
 - Sustainability



- 3 technologies**
 - Ampoc Wing
 - AMPOC ECO
 - AMPOC 5A

03

Financial Information



2021~2023H1 Consolidated Balance sheet

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2021	2022	2023 H1
Net Revenue		2,938,974	3,448,384	1,640,864
Gross profit		778,114	1,098,413	617,516
Gross margin(%)		26.48	31.85	37.63
Operating income		453,574	756,369	415,770
Net income after tax		343,298	592,400	343,130
EPS		3.00	5.18	3.00



==== 2021~2023H1 Consolidated Income statement ====

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2021	2022	2023 H1
Current Assets		3,145,641	3,992,366	4,101,393
Non-current Assets		695,569	633,581	614,516
Total Assets		3,841,210	4,625,947	4,715,909
Current Liabilities		1,282,260	1,762,805	1,976,926
Non-current Liabilities		119,162	98,176	99,738
Total Liabilities		1,401,422	1,860,981	2,076,664



2021~2023H1 Financial Analysis

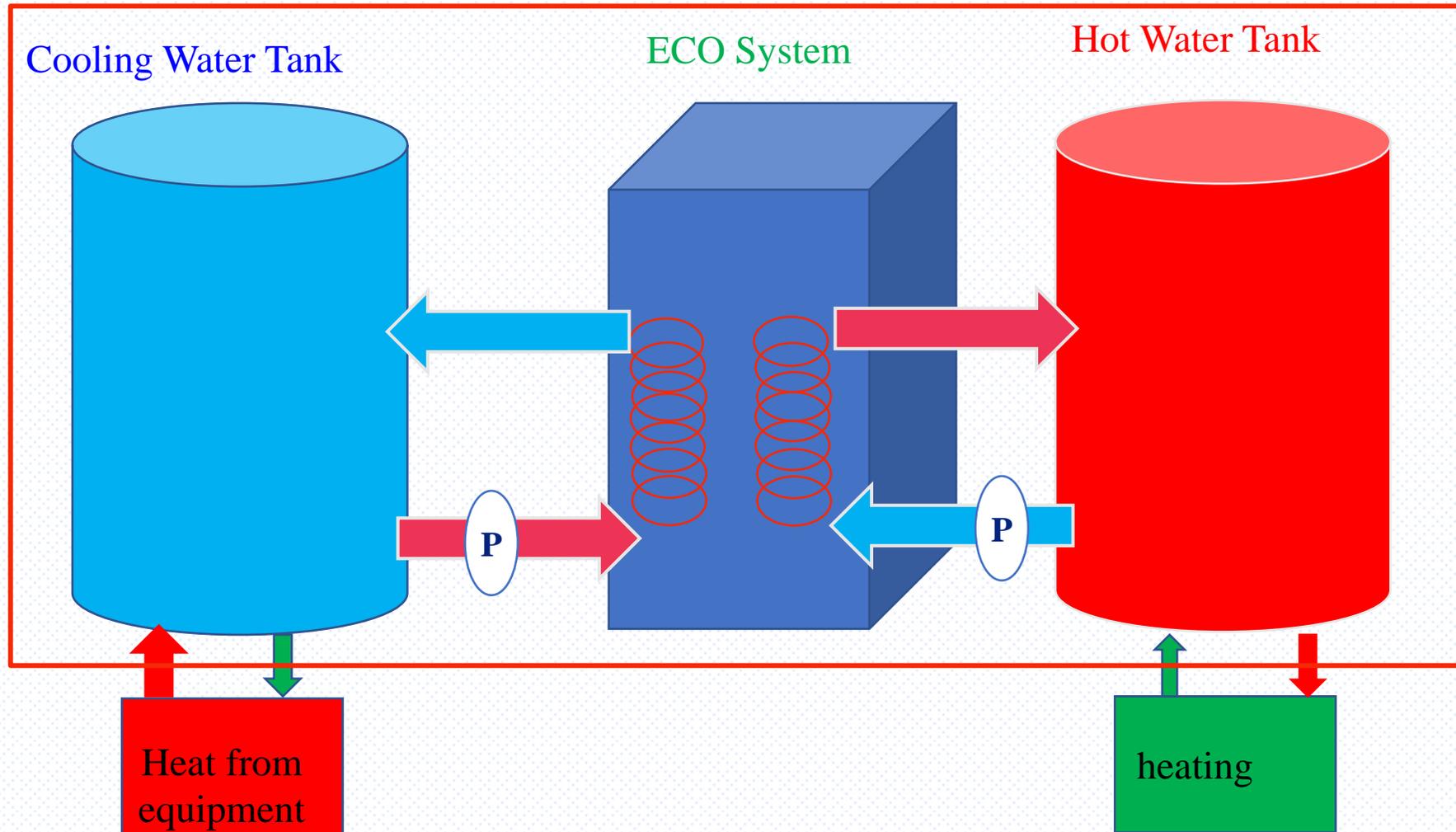
Item	Year	2021	2022	2023 H1
Debts Ratio(%)		36.48	40.23	44.04
Current Ratio(%)		245.32	226.48	207.46
Average Inventory Turnover(Times)		1.91	1.91	1.73
Return on Equity (%)		14.32	22.76	12.70

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**Own Brand Equipment
- Introduction and Prospect**



ECO System heat exchange





- A. 2023 H1 own brand equipment is mainly for IC substrate, HDI, SLP manufacturing. The applications include smart phone, automobile, servers, etc.
- B. New patented product AMPOC 5A (Arrows) is available this year and will be public introduced in 2023 TPCA show. The new patented design ECO system is considered as a good response to global warming problems and a measure for energy saving and carbon reduction demands.
- C. Prospect for new equipment development and demand :
 1. Advanced ABF substrate process equipment demand
 2. Advanced product competition among PCB makers, including 5G related substrates, SLP, HDI and FPCB process equipment demands
 3. Electric Vehicles and security related PCB equipment demand
 4. Energy saving and waste reduction equipment is now under development

05

Distribution Business

- Introduction and Prospect



先進封裝設備/材料/檢測解決方案





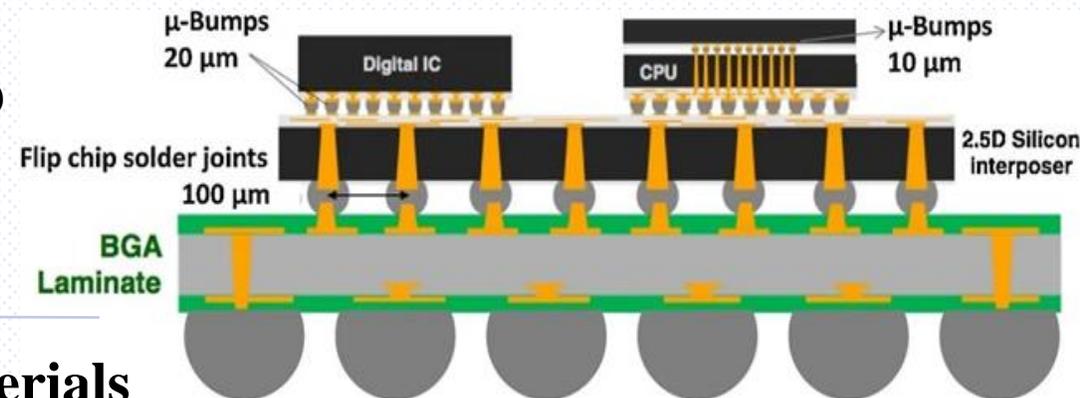
Material

Advanced Packaging

- ➔ Micro Bumping/SnAg (for mass production)
- ➔ Cu Pillar (for mass production)
- ➔ Dielectric (developing)

Semicon Front-end process materials

- ➔ Lithograph materials
- ➔ Domestic and overseas markets foundries (testing)



2.5D/3D IC 封裝結構的橫截面圖

資料來源: <https://www.eettaiwan.com/20221220nt41-3d-ic-ma-tek/>

Equipment

AI/5G

- ➔ 2.5D Bonder (testing)
- ➔ 3D Bonder (end customer product verification testing)

Application

- ➔ Chip On Wafer on Substrate
 - ➔ HPC
 - ➔ Silicon Photonics
- } AI



Thank you for
your Attention!